Down-Hole Applications

Why use Epoxies for Down-Hole Applications?

Epoxies are very robust materials that can withstand harsh conditions, such as high temperature, high pressure, and mechanical shock.

Down-hole applications include:

- Electrical connections within a microelectronic package (die attach, capacitor attach)
- Protected thermal connections (heat sinking, capacitor attach)
- Potting compound to encapsulate electronics and protect them from the environment
- · Fiber optic cabling and interconnected sensor devices

Which EPO-TEK® Products Are Best Suited for Down-Hole Applications?

- Electrically Conductive Component Attach
 - High Temperature Exposure: H20E, H20E-175, H24, H35-175MP, H37-MP
 - Heat Sinking: EK1000-1
- Non-Conductive Component Attach
 - High Temperature Exposure: H65-175MP, H67-MP, H74, H77
 - Heat Sinking: T905BN-3, 930-4

- Potting & Protection
 - Small Volume: 302-3M, 353ND, OD2002
 - Thermally Conductive: H77, T905BN-3
- High Temperature Resistant Materials (260°C-300°C)
 - Low Viscosity Pourable Liquid: 118-150-2
 - Thixotropic Paste: 120-183-3
- Fiberoptic Bundles
 - Low Viscosity and Wicking: 353ND, 377

Characteristics To Help Choose the Correct EPO-TEK® Product

EPO-TEK	Key advantages/ Characteristics										
118-150-2	Pourable liquid with enhanced performance above 260°C										
120-183-3	Thixotropic paste with enhanced performance above 260°C										
302-3M	Proven saline resistance for a harsh chemical environment										
353ND	Strong chemical and moisture resistance (reliable industry standard)										
377	Strong chemical and moisture resistance, long pot life										
930-4	Non conductive, high ThK with small particle filler for small gaps										
EK1000-1	ECA with highest measured ThK										
H20E	ECA with high ThK, rheology ideal for multiple application types										
H20E-175	ECA, higher temperature rated version of H20E										
H24	ECA with very high degradation temperature										
H35-175MP*	High strength ECA										
H37-MP*	High strength and high thixotropy ECA										
H65-175MP*	ThK version of H35-175MP										
H67-MP*	High thixotropy, ThK version of H37-MP										
H74	Strong chemical resistance, plus ThK										
H77	Potting compound with good chemical resistance for protection of parts										
OD2002	Strong chemical, moisture and impact resistance										
T905BN-3	High ThK, designed for large volume potting										
CCA Flootrical	A Floatricelly Conductive Adhesives * MD Military Approved Thy Thermally Conductive										

ECA - Electrically Conductive Adhesives, * MP - Military Approved, ThK - Thermally Conductive





How Do The EPO-TEK Properties Compare?

T905BN-3	002002	Н77	H74	H67-MP*	H65-175MP*	H37-MP*	H35-175MP*	H24	H20E-175	H20E	EK1000-1	930-4	377	353ND	302-3M	120-183-3	118-150-2	EPO-TEK®
Two	Two	Two	Two	0ne	0ne	0ne	0ne	Two	Two	Two	One	Two	Two	Two	Two	One	0ne	NO. of COMPONENTS
Grey/Grey	Cloudy/Ivory	Grey/Grey	Grey/ Dark Grey	lvory/lvory	lvory/lvory	Silver/Silver	Silver/Silver	Silver/Silver	Silver/Silver	Silver/Silver	Silver/Silver	lvory/Amber	Clear/Amber	Amber/ Dark Red	Clear/ Colorless	Off White/Tan	Clear/Amber	COLOR Before/ After CURE (thin film)
80°C – 2 hours	150°C – 5 min 100°C – 30 min	150°C – 1 hour	150°C – 5 min 100°C – 20 min	150°C – 1 hour	180°C – 1 hour	150°C – 1 hour	180°C – 1 hour 165°C – 90 min	150°C – 5 min 80°C – 45 min	180°C – 1 hour 150°C – 2 hours	175°C – 45 sec 80°C – 3 hours	[150°C - 1 hour +] [200°C - 1 hour] 200°C - 30 min	150°C – 10 min 100°C – 4 hours 80°C – 6 hours	150°C – 1 hour	150°C – 1 min 80°C – 30 min	65°C – 3 hours 23°C – 24 hours	120°C – 1 hour + 177°C – 1 hour + 265°C – 2 hours	80°C - 1 hour + 150°C - 1 hour + 177°C - 2 hours	CURE TEMPERATURE (minimal)
2,000 - 7,000 cPs @ 50 rpm	24,000 - 42,000 cPs @ 2.5 rpm	6,000 - 12,000 cPs @ 20 rpm	45,000 - 65,000 cPs @ 5 rpm	300,000 - 400,000 cPs @ 1 rpm	80,000 - 120,000 cPs @ 2.5 rpm	22,000 - 26,000 cPs @ 10 rpm	22,000 - 28,000 cPs @ 10 rpm	15,000 - 23,000 cPs @ 10 rpm	2,800 - 3,800 cPs @ 100 rpm	2,200 - 3,200 cPs @ 100 rpm	13,000 - 21,000 cPs @ 10 rpm	12,000 - 17,000 cPs @ 20 rpm	150 - 300 cPs @ 100 rpm	3,000 - 5,000 cPs @ 50 rpm	800 - 1,600 cPs @ 100 rpm	124,928 cPs @ 1 rpm	8,724 cPs @ 20 rpm	VISCOSITY @ 23°C
≥40°C	>140°C	≥80°C	≥100°C	≥90°C	≥100°C	≥90°C	≥100°C	≥100°C	≥85°C	≥80°C	2°08≤	2°06≅	≥95°C	2°06≅	≥55°C	255°C	264°C	GLASS TRANSITION TEMPERATURE (Tg)
≥10 kg/3,400 psi	≥10 kg/3,400 psi	≥5 kg/1,700 psi	≥15 kg/5,100 psi	≥20 kg/6,800 psi	≥20 kg/6,800 psi	≥10 kg/3,400 psi	≥10 kg/3,400 psi	≥5 kg/1,700 psi	≥10 kg/3,400 psi	>10 kg/3,400 psi	≥10 kg/3,556 psi	≥15 kg/5,100 psi	≥10 kg/3,400 psi	≥15 kg/5,100 psi	≥10 kg/3,400 psi	≥7 kg/2,380 psi	13 kg/4,420 psi	DIE SHEAR STRENGTH @ RT (80mil x 80mil)
N/A	1.5728 (uncured)	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	1.5195 (uncured)	1.5694 (uncured)	1.5446 (uncured)	N/A	1.5850 (uncured)	INDEX OF REFRACTION (Nd)
N/A	>98% @ 800-1640nm	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	>90% @ 600-1000nm >98% @ 1000-6800nm	>50% @ 550nm >98% @ 800-1000nm >95% @ 1100-1600nm	>95% @ 460-1620nm	N/A	N/A	SPECTRAL TRANSMISSION
347°C	443°C	405°C	425°C	350°C	397°C	358°C	372°C	470°C	450°C	425°C	372°C	425°C	375°C	412°C	351°C	443°C	264°C	TGA DEGRADATION TEMPERATURE
37 x 10 ⁻⁶ 151 x 10 ⁻⁶	45 x 10 ⁻⁶ 187 x 10 ⁻⁶	33 x 10 ⁻⁶ 130 x 10 ⁻⁶	21 x 10 ⁻⁶ 95 x 10 ⁻⁶	16 x 10 ⁻⁶ 68 x 10 ⁻⁶	38 x 10 ⁻⁶ 136 x 10 ⁻⁶	52 x 10 ⁻⁶ 148 x 10 ⁻⁶	31 x 10 ⁻⁶ 97 x 10 ⁻⁶	28 x 10 ⁻⁶ 104 x 10 ⁻⁶	20 x 10 ⁻⁶ 88 x 10 ⁻⁶	31 x 10 ⁻⁶ 158 x 10 ⁻⁶	41 x 10 ⁻⁶ 162 x 10 ⁻⁶	27 x 10 ⁻⁶ 136 x 10 ⁻⁶	57 x 10 ⁻⁶ 210 x 10 ⁻⁶	54 x 10 ⁻⁶ 206 x 10 ⁻⁶	56 x 10 ⁻⁶ 193 x 10 ⁻⁶	46 x 10-6 85 x 10-6	47 x 10 ⁻⁶ 219 x 10 ⁻⁶	CTE Below Tg/ Above Tg (in/in/°C)
3 hours	4 hours	6 hours	2 hours	28 days	28 days	28 days	28 days	18 hours	3.5 days	2.5 days	2 weeks	1 day	24 hours	≤3 hours	1 hour	16 hours	16 hours	POT LIFE (@ room temp.)
1 year	1 year	1 year	1 year	1 year @ -40°C	1 year @ -40°C	1 year @ -40°C	1 year @ -40°C	6 months	1 year	1 year	1 year @ -40°C	1 year	1 year	1 year	1 year	1 year @ -40°C	1 year @ -40°C	SHELF LIFE (@ room temp. unless noted)
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^{*} MP - Military Approved, N/A - not available/applicable

at: techserv@epotek.com. to find the most suitable adhesives for specific technical challenges Please consult our Application Experts at Epoxy Technology



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